

Title (en)

METHOD FOR FABRICATION OF ANISOTROPIC CONDUCTIVE MEMBER AND METHOD FOR FABRICATION OF ANISOTROPIC CONDUCTIVE BONDING PACKAGE

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES ANISOTROPEN LEITFÄHIGEN ELEMENTS UND VERFAHREN ZUR HERSTELLUNG EINER ANISOTROPEN LEITFÄHIGEN BONDINGVERKAPSELUNG

Title (fr)

PROCÉDÉ DE FABRICATION D'ÉLÉMENT CONDUCTEUR ANISOTROPE ET PROCÉDÉ DE FABRICATION DE BOÎTIER DE COLLAGE CONDUCTEUR ANISOTROPE

Publication

EP 3026764 A1 20160601 (EN)

Application

EP 14830337 A 20140718

Priority

- JP 2013151603 A 20130722
- JP 2014069239 W 20140718

Abstract (en)

Provided is a method for fabrication of an anisotropic conductive member, the method including a residual stress relaxation step of obtaining an anisotropic conductive member that has been subjected to a treatment for relaxing residual stress, after fabricating an anisotropic conductive member having plural conductive paths, in which plural micropores of an insulating matrix formed from an anodic oxide film are filled with a conductive member.

IPC 8 full level

H01R 43/00 (2006.01); **C25D 1/00** (2006.01); **C25D 5/50** (2006.01); **C25D 11/04** (2006.01); **C25D 11/18** (2006.01); **C25D 11/20** (2006.01); **C25D 11/24** (2006.01); **H01B 5/16** (2006.01); **H01B 13/00** (2006.01); **H01R 11/01** (2006.01); **C23C 18/16** (2006.01); **C25D 3/38** (2006.01); **C25D 11/10** (2006.01); **C25D 11/16** (2006.01)

CPC (source: EP US)

C25D 1/006 (2013.01 - EP US); **C25D 5/50** (2013.01 - EP US); **C25D 11/045** (2013.01 - EP US); **C25D 11/18** (2013.01 - EP US); **C25D 11/20** (2013.01 - EP US); **C25D 11/24** (2013.01 - EP US); **C23C 18/1603** (2013.01 - EP US); **C23C 18/1653** (2013.01 - EP US); **C25D 3/38** (2013.01 - EP US); **C25D 11/10** (2013.01 - EP US); **C25D 11/16** (2013.01 - EP US)

Cited by

EP3571744A4; WO2018145287A1; WO2019016036A1; US11028496B2; US11618966B2; US11827992B2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 3026764 A1 20160601; **EP 3026764 A4 20161116**; CN 105431987 A 20160323; JP 2017022126 A 20170126; JP 6030241 B2 20161124; JP 6166826 B2 20170719; JP WO2015012234 A1 20170302; KR 101795538 B1 20171108; KR 20160023844 A 20160303; US 2016138180 A1 20160519; WO 2015012234 A1 20150129

DOCDB simple family (application)

EP 14830337 A 20140718; CN 201480041699 A 20140718; JP 2014069239 W 20140718; JP 2015528275 A 20140718; JP 2016170735 A 20160901; KR 20167001900 A 20140718; US 201615003154 A 20160121